















**ESD** 

TVS

MOS

LDO

Diode

Sensor

DC-DC

# **Product Specification**

Domestic Part Number	IPD60R360P7
<ul><li>Overseas Part Number</li></ul>	IPD60R360P7
▶ Equivalent Part Number	IPD60R360P7





### Description

Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFET, designed according to the SJ principle. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

### **Features**

- Very low FOM RDS(on)×Qg
- 100% UIS tested
- RoHS compliant

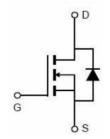
### **Applications**

- Power factor correction (PFC).
- Switched mode power supplies (SMPS).
- Uninterrupted power supply (UPS).

### **Product Summary**

 $\begin{array}{lll} V_{DS} \textcircled{@} \ T_{j,25^{\circ}} & 650V \\ R_{DS(on),max} & 0.38 \, \Omega \\ I_{D} & 11A \\ Q_{g,typ} & 19.2nC \end{array}$ 

# **TO-252-2L Pin Configuration**





### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	650	V	
Continuous drain current ( T <sub>C</sub> = 25°C )	I <sub>D</sub>	11	Α	
( T <sub>C</sub> = 100°C )		7	Α	
Pulsed drain current 1)	I <sub>DM</sub>	33	Α	
Gate-Source voltage	V <sub>GSS</sub>	±30	V	
Avalanche energy, single pulse 2)	E <sub>AS</sub>	210	mJ	
Avalanche current, repetitive 3)	I <sub>AR</sub>	1.6	Α	
Power Dissipation TO-263 (T <sub>C</sub> = 25°C)		125	W	
- Derate above 25°C	P <sub>D</sub>	1	W/°C	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	
Continuous diode forward current	Is	11	Α	
Diode pulse current	I <sub>S,pulse</sub>	33	Α	



#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
		TO-263	
Thermal Resistance, Junction-to-Case	R <sub>BJC</sub>	1	°CMV
Thermal Resistance, Junction-to-Ambient	R <sub>BJA</sub>	62.5	°CMV
Soldering temperature, wave soldering only allowed at leads. (1.6mm from case for 10s)	T <sub>sold</sub>	260	°C

#### Electrical Characteristics T<sub>c</sub> = 25°C unless otherwise noted

Parameter	Symbol	<b>Test Condition</b>	Min.	Тур.	Max.	Unit
Static characteristics	•		•			
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250uA	650	-	-	V
Gate threshold voltage	V <sub>GE(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2.0	3.0	4.0	V
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> =650 V, V <sub>GS</sub> =0 V,				μА
		T <sub>j</sub> = 25°C	-	-	1	
		T <sub>j</sub> = 125°C	- 1	10		
Gate leakage current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =30 V, V <sub>DS</sub> =0 V	-	-	100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-30 V, V <sub>DS</sub> =0 V	-	-	-100	nA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =5.5 A	21			
		T <sub>j</sub> = 25°C	-	330	380	mΩ
			-			
Dynamic characteristics						
Input capacitance	Ciss	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V,	-	852	-	
Output capacitance	Coss	f = 1MHz	¥1	37	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	]	-	2.0	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 400V, I <sub>D</sub> = 5.5A	-1	16	-	
Rise time	t <sub>r</sub>	$R_G = 25\Omega$ , $V_{GS}=10V$	-	35	-	ns
Turn-off delay time	t <sub>d(off)</sub>	1	-	78	-	
Fall time	t <sub>f</sub>	1	-	39.5	-	
Gate charge characteristics					ta v	
Gate to source charge	Q <sub>gs</sub>	V <sub>DD</sub> =520 V, I <sub>D</sub> =5.5A,	-	3.1	-	
Gate to drain charge	$Q_{gd}$	V <sub>GS</sub> =0 to 10 V	-	8.2	-	nC
Gate charge total	Qg	1	-	19.2	-	
Gate plateau voltage	V <sub>plateau</sub>	1	-	5.5	-	V
Reverse diode characteristics		•			I.	
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0 V, I <sub>S</sub> =11A	-	-	1.4	V
Reverse recovery time	t <sub>rr</sub>	V <sub>R</sub> =400 V, I <sub>F</sub> =5.5A,	-	310	-	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>F</sub> /dt=100 A/μs	H	2.8	-	μC
Peak reverse recovery current	I <sub>m</sub>	1		16	-	Α

#### Notes:

<sup>1.</sup> Limited by maximum junction temperature, maximum duty cycle is 0.75.

<sup>2.</sup>  $I_{AS}$  = 3A,  $V_{DD}$  = 50V, Starting  $T_j$ = 25°C.



#### **Electrical Characteristics Diagrams**

Figure 1. Output Characteristics

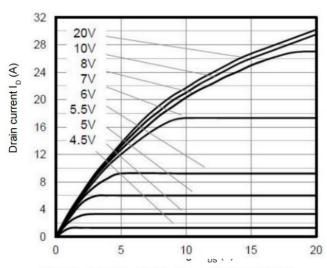


Figure 3. On-Resistance vs. Drain Current

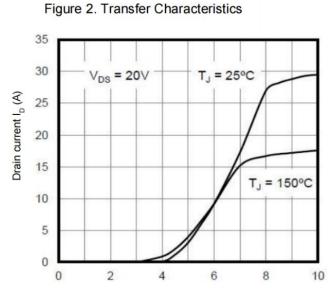


Figure 4. Capacitance Characteristics

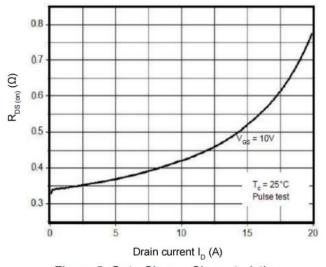
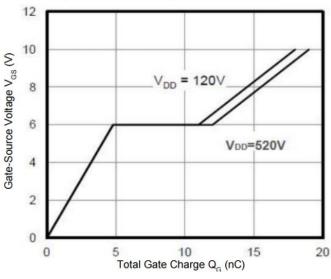
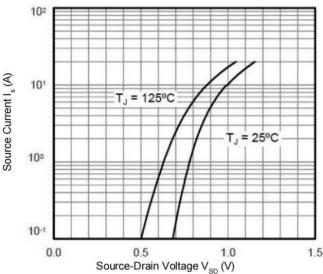


Figure 5. Gate Charge Characteristics



10<sup>3</sup>
(d) and a contribution of the contributi

Figure 6. Body Diode Forward Voltage





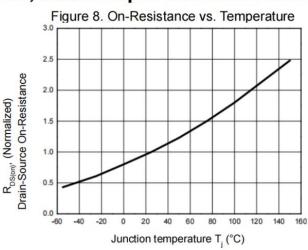
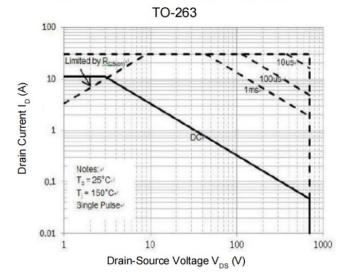


Figure 9. Maximum Safe Operating Area

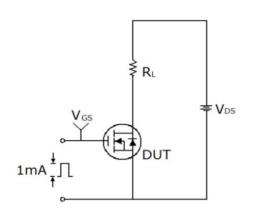


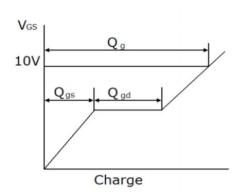


#### **Test Circuits**

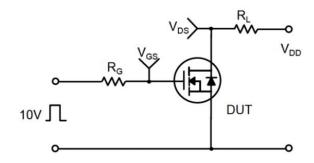
# N-channel 650V, 11A, $0.38\Omega$ Super-Junction Power MOSFET

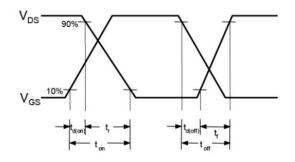
#### **Gate Charge Test Circuit & Waveform**



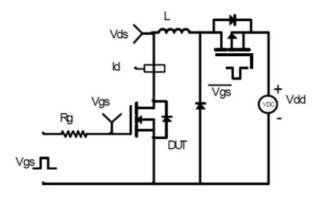


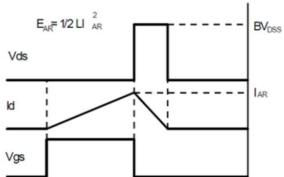
#### **Switching Test Circuit & Waveform**





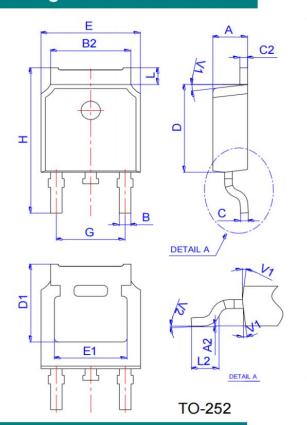
#### **Unclamped Inductive Switching Test Circuit & Waveform**





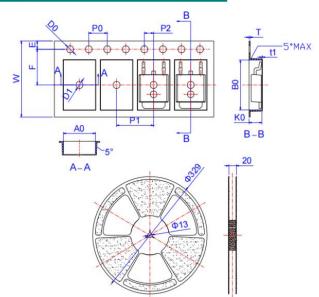


# Package Mechanical Data



	Dimensions							
Ref.	Millimeters			Inches				
	Min.	Typ.	Max.	Min.	Тур.	Max.		
Α	2.10		2.50	0.083		0.098		
A2	0		0.10	0		0.004		
В	0.66		0.86	0.026		0.034		
B2	5.18		5.48	0.202		0.216		
С	0.40		0.60	0.016		0.024		
C2	0.44		0.58	0.017		0.023		
D	5.90		6.30	0.232		0.248		
D1	5.30REF			0.209REF				
E	6.40		6.80	0.252		0.268		
E1	4.63			0.182				
G	4.47		4.67	0.176		0.184		
Н	9.50		10.70	0.374		0.421		
L	1.09		1.21	0.043		0.048		
L2	1.35		1.65	0.053		0.065		
V1		7°			7°			
V2	0°		6°	0°		6°		

# **Reel Spectification-TO-252**



	Dimensions						
Ref.		Millimete	rs	Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
W	15.90	16.00	16.10	0.626	0.630	0.634	
Е	1.65	1.75	1.85	0.065	0.069	0.073	
F	7.40	7.50	7.60	0.291	0.295	0.299	
D0	1.40	1.50	1.60	0.055	0.059	0.063	
D1	1.40	1.50	1.60	0.055	0.059	0.063	
P0	3.90	4.00	4.10	0.154	0.157	0.161	
P1	7.90	8.00	8.10	0.311	0.315	0.319	
P2	1.90	2.00	2.10	0.075	0.079	0.083	
A0	6.85	6.90	7.00	0.270	0.271	0.276	
B0	10.45	10.50	10.60	0.411	0.413	0.417	
K0	2.68	2.78	2.88	0.105	0.109	0.113	
Т	0.24		0.27	0.009		0.011	
t1	0.10			0.004			
10P0	39.80	40.00	40.20	1.567	1.575	1.583	



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